



Resin Bond Diamond Dicing Blade

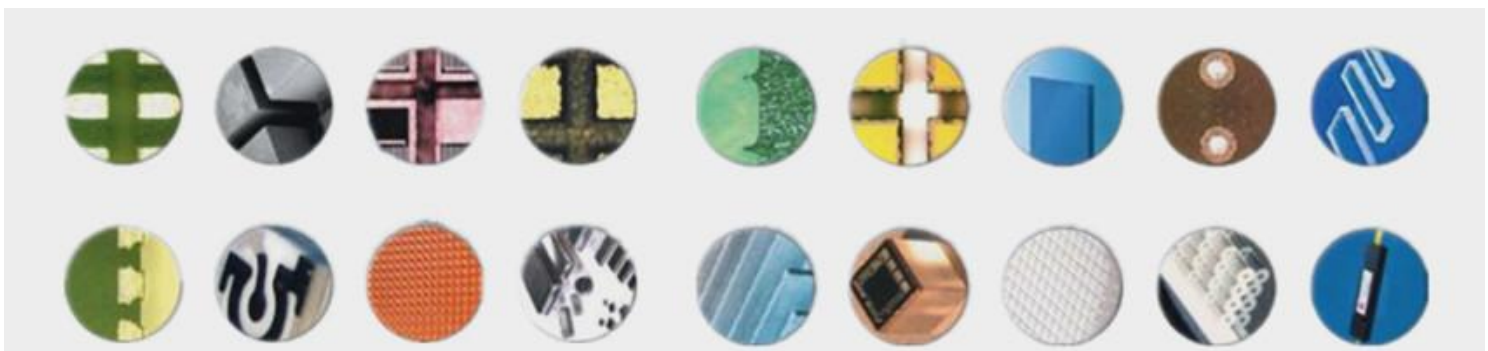
Resin dicing blade is suited for cutting hard and brittle materials, such as QFN, sapphire, quartz and glass, etc. You can rest assured to buy Resin Bond Diamond Dicing Blade from our factory.

Buy Resin Bond Diamond Dicing Blade from China Factory

- * Excellent cutting ability that help reduce chipping, fractures and achieve smooth surface finish
- * Dicing hard and brittle materials. Such as QFN/MLF, Thick Ceramic Substrates and Glass, etc
- * Able to precisely control diamond concentration to achieve cutting quality
- * Self sharpening matrix to expose new diamonds. Diamond grit size ranges from 3 μ m to 250 μ m depending on blade thickness

Applications of Resin Bond Diamond Dicing Blade

Glass (optical devices, fiber optics), quartz (optical splitters, saw devices), LiTaO₃ LiNbO₃ (devices), QFN (copper epoxy molding), splitter, sapphire



With advanced technologies and facilities, strict high quality control, reasonable value, exceptional company and close co-operation with prospects, we've been devoted to offering the very best worth for our consumers for Lowest Price for China Diamond Cutting Blade for Wafering and Dicing, We welcome customers, business associations and friends from all parts of the world to contact us and



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seek cooperation for mutual benefits. Lowest Price for China Resin Bond Diamond Cutting Blade, Resin Bond Diamond Dicing Blade, Our advanced equipment, excellent quality management, research and development ability make our price down. The price we offering may not be the lowest, but we guarantee it is absolutely competitive! Welcome to contact us immediately for future business relationship and mutual success!